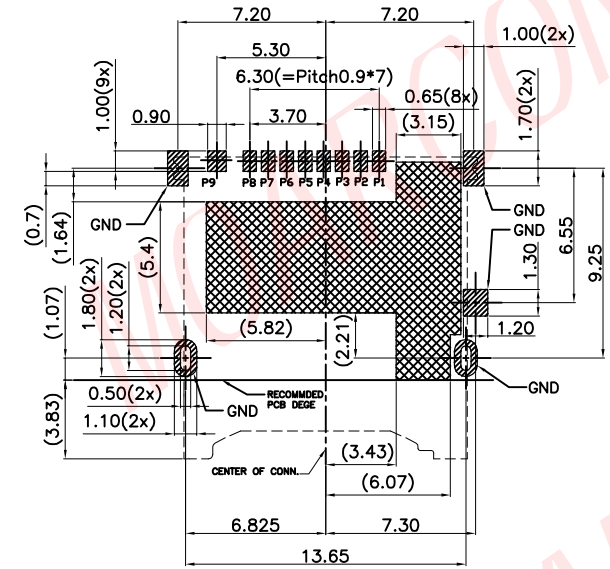
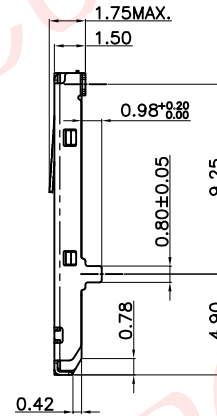
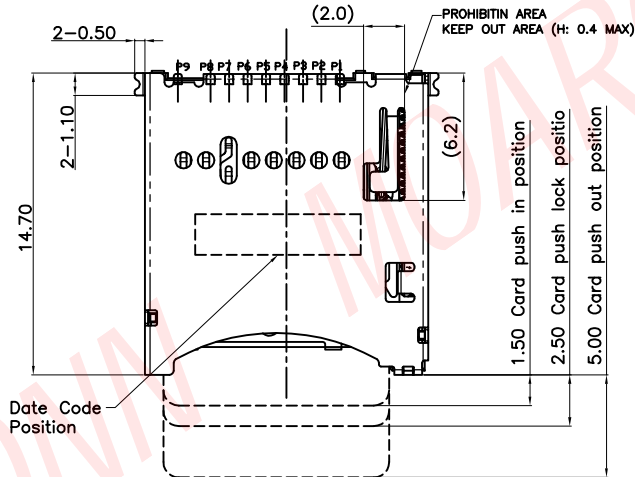
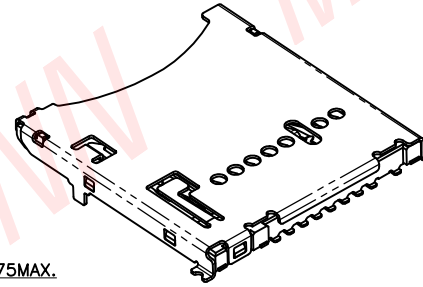
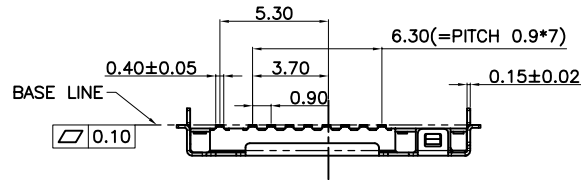


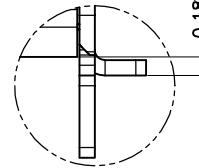
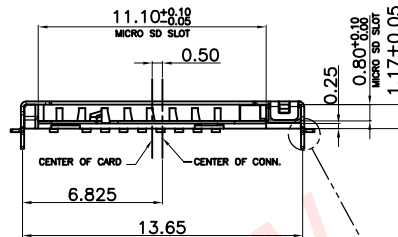
All materials, plating and process meet HF requirements.



▨ PAD AREA

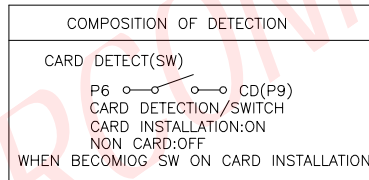
▩ No trace, no test point, no via hole, no ground area

PCB PATTERN LAYOUT
(GENERAL TOLERANCE:±0.05)



Detail A
Scale 5 : 1

Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1
P9	CD



Specification
 *Electrical Characteristics:
 Contact Current Rating:0.5Amperes.
 Dielectric Withstanding Voltage:AC500V r.m.s.
 Insulation Resistance:1000 Megohms
 Minimum At DC 500V.
 Contact Resistance:100 mΩ Maximum.
 *Mechanical Characteristics:
 Mating Cycles:10,000 Cycles.
 *Environmental:
 Operating Temperature:-25°C~+85°C.
 *Materials:
 Insulator:HI-Temp plastic (LCP,S475),UL Black 94V-0.
 Contact:Phosphor Bronze(C5210-EH,T=0.10±0.03mm)
 Shell:SUS304-1/2H T=0.15±0.03mm
 *Plating:
 Contact: Plated 50u"min Ni Overall
 Plated 1u"min Au Selective Contact Area
 Plated 80u"min Sn over Ni on solder area
 Shell: Plated 50u"min Ni Overall

MOARCONN
MORE CONNECTIONS SMART FUTURE

DONG GUAN MOARCONN ELECTRONIC Co.,Ltd.

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2'

PRODUCT NAME : Micro SD P-P TOP MOUNT H=1.50mm	DRAWING: PURE	DATE: 2019.08.31
PRODUCT NO. : MC150-T1251-11	CHECK:	DATE:
DRAWING NO. : D-MC150-T1251-11	APPROVED:	DATE:
SCALE: 1:1	DWG ID: C D	REV.: B
		PAGE: 1 of 1

B	ECN20190902001	Modify the plating specification of shell	PURE	2019.08.31
A	---	NEW RELEASE	Janyz	2019.08.21
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE